

Type number	Package	Package description	Total product weight
BC860BW	SOT323	SC-70	5.52641 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
934024340135	13	1	260	30 s	1	235	20 s	3	Dongguan, China; Seremban, Malaysia; D-22529 HAMBURG, Germany	
934024340115	12	1	260	30 s	1	235	20 s	3	Seremban, Malaysia; Dongguan, China; D-22529 HAMBURG, Germany	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.04000	100.00000	0.72380
		subTotal		0.04000	100.00000	0.72380
Lead Frame	Iron-nickel alloy	Aluminium (Al)	7429-90-5	0.00166	0.09000	0.03013
		Carbon (C)	7440-44-0	0.00074	0.04000	0.01339
		Chromium (Cr)	7440-47-3	0.00166	0.09000	0.03013
		Cobalt (Co)	7440-48-4	0.00796	0.43000	0.14395
		Iron (Fe)	7439-89-6	0.82602	44.65000	14.94686
		Manganese (Mn)	7439-96-5	0.01276	0.69000	0.23098
		Nickel (Ni)	7440-02-0	0.63899	34.54000	11.56248
		Phosphorus (P)	7723-14-0	0.00037	0.02000	0.00670
		Silicon (Si)	7440-21-3	0.00481	0.26000	0.08704
		Sulphur (S)	7704-34-9	0.00037	0.02000	0.00670
	Pure metal layer	Copper (Cu)	7440-50-8	0.31172	16.85000	5.64064
		Silver (Ag)	7440-22-4	0.04292	2.32000	0.77663
		subTotal		1.85000	100.00000	33.47563
Mould Compound	Filler	Silica fused	60676-86-0	2.55340	75.10000	46.20359
	Pigment	Carbon black	1333-86-4	0.01020	0.30000	0.18457
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	0.59500	17.50000	10.76648
		Phenol Formaldehyde resin (generic)	9003-35-4	0.24140	7.10000	4.36812
		subTotal		3.40000	100.00000	61.52276
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00001	0.00300	0.00012
		Bismuth (Bi)	7440-69-9	0.00000	0.00100	0.00004
		Copper (Cu)	7440-50-8	0.00000	0.00100	0.00004
		Lead (Pb)	7439-92-1	0.00001	0.00500	0.00021
	Tin solder	Tin (Sn)	7440-31-5	0.22998	99.99000	4.16142
		subTotal			0.23000	100.00000
Wire	Pure metal	Copper (Cu)	7440-50-8	0.00641	100.00000	0.11593
		subTotal			0.00641	100.00000

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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